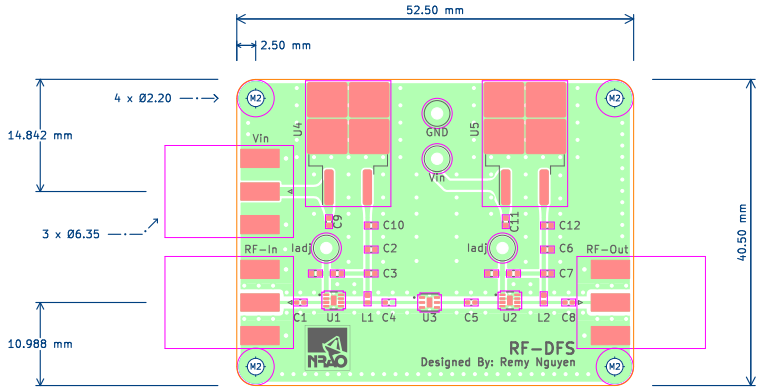
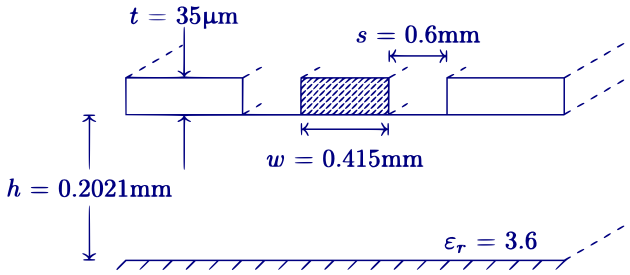
TOP-L1





Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm		
Min track/spacing:	0.415 mm / 0.300 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

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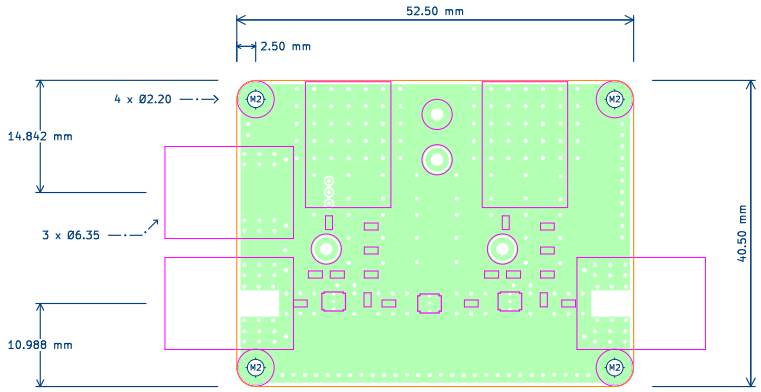
IN-L2



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm		
Min track/spacing:	0.415 mm / 0.300 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

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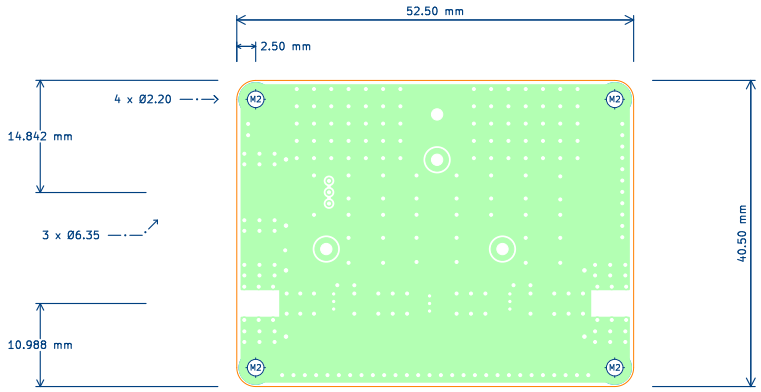
IN-L3



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm		
Min track/spacing:	0.415 mm / 0.300 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

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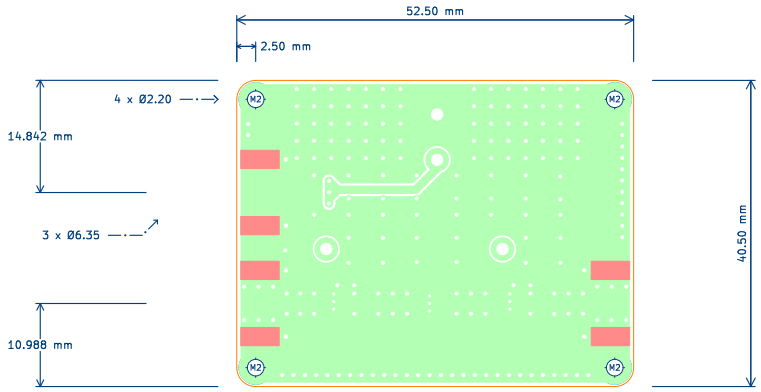
BOT-L4



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm		
Min track/spacing:	0.415 mm / 0.300 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

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Title: RF-DFS Gain Circuit

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